

P-Channel MOSFET

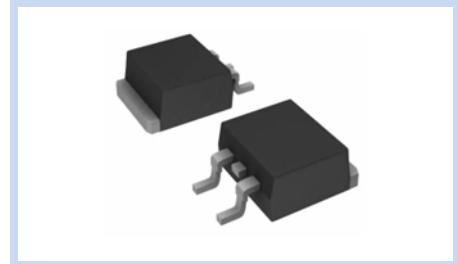
60V 40A TO-263

MFT6P40T263

MERITEK

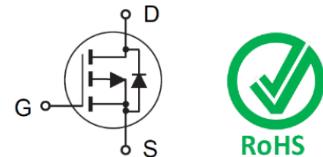
FEATURE

- $R_{DS(ON)}=19\text{m}\Omega$ at $V_{GS}=-10\text{V}$, $I_D=-40\text{A}$
- $R_{DS(ON)}=25\text{m}\Omega$ at $V_{GS}=-4.5\text{V}$, $I_D=-40\text{A}$
- High Power and Current Handling Capability
- Super High Dense Cell Design for Extremely Low $R_{DS(ON)}$



MECHANICAL DATA

- Case: TO-263 Package
- Terminals: Solderable per MIL-STD-750, Method 2026

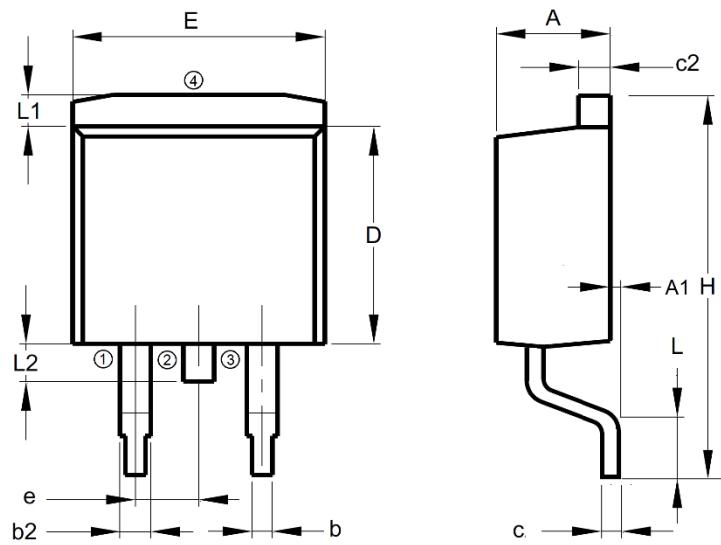


MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-60	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current – Continuous	I_D	-40	A
		-25	
Drain Current – Pulsed	I_{DM}	-160	A
Power Dissipation	P_D	60	W
		0.48	W/ $^{\circ}\text{C}$
Single Pulsed Avalanche Energy	E_{AS}	113	mJ
Single Pulsed Avalanche Current	I_{AS}	15	A
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	62.5	$^{\circ}\text{C}/\text{W}$
Thermal Resistance Junction to Case	$R_{\theta JC}$	2.1	$^{\circ}\text{C}/\text{W}$
Operating Junction and Storage Temperature	T_J , T_{STG}	-55 to 150	$^{\circ}\text{C}$

DIMENSIONS

Item	Min (mm)	Max (mm)
A	4.29	4.70
A1	--	0.25
b	0.69	0.94
b2	1.22	1.40
c	0.36	0.56
c2	1.22	1.40
D	8.64	9.65
E	9.70	10.54
e	2.29	2.79
H	14.61	15.88
L	2.24	2.84
L1	--	1.40
L2	0.96	1.78



Note: 1: Gate, 2: Drain, 3: Source

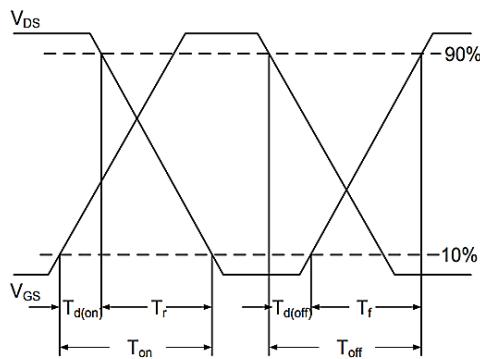
ELECTRICAL CHARACTERISTICS

Off Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	BV_{DSS}	-60	-	-	V
Drain-Source Leakage Current	$V_{DS}=-60V, V_{GS}=0V$	I_{DSS}	-	-	-1	μA
Gate-Body Leakage Current, Forward	$V_{GS}=20V, V_{DS}=0V$	I_{GSSF}	-	-	100	nA
Gate-Body Leakage Current, Reverse	$V_{GS}=-20V, V_{DS}=0V$	I_{GSSR}	-	-	-100	nA
On Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
Static Drain-Source On-Resistance	$V_{GS}=-10V, I_D=30A$	$R_{DS(on)}$	-	15	19	$m\Omega$
	$V_{GS}=-4.5V, I_D=30A$		-	18	25	$m\Omega$
Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	$V_{GS(th)}$	-1	-	-3	V
Dynamic Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
Total Gate Charge	$V_{DS}=80V, V_{GS}=10V, I_D=30A$	Q_g	-	38	-	nC
Gate-Source Charge		Q_{gs}	-	8	-	
Gate-Drain Charge		Q_{gd}	-	18	-	
Turn-On Delay Time	$V_{DD}=-48V, V_{GS}=-10V, R_G=6\Omega, I_D=-20A$	$T_{d(on)}$	-	18	-	ns
Rise Time		T_r	-	10	-	
Turn-Off Delay Time		$T_{d(off)}$	-	115	-	
Fall Time		T_f	-	38	-	
Input Capacitance	$V_{DS}=-25V, V_{GS}=0V, F=1MHz$	C_{iss}	-	2845	-	pF
Output Capacitance		C_{oss}	-	295	-	
Reverse Transfer Capacitance		C_{rss}	-	165	-	
Drain-Source Body Diode	Conditions	Symbol	Min	Typ.	Max	Unit
Drain-Source Diode Forward Current	--	I_s	-	-	-40	A
Diode Forward Voltage	$V_{GS}=0V, I_s=-20A, T_J=25^\circ C$	V_{SD}	-	-	-1.2	V

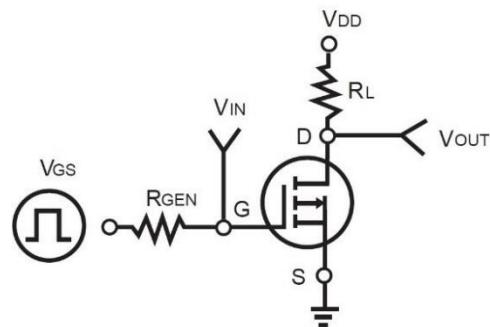
Note:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$
3. Guaranteed by design, not subject to production testing.
4. $L=1mH, I_{AS} = 15A, V_{DD} = 24V, R_G=25\Omega$, Starting $T_J=25^\circ C$

Switching Time Waveform



Switching Test Circuit



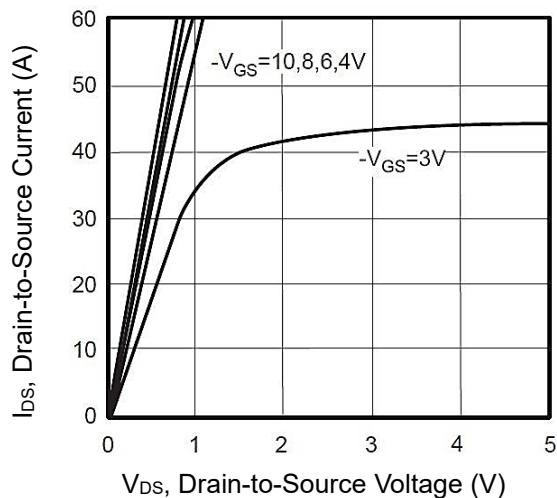
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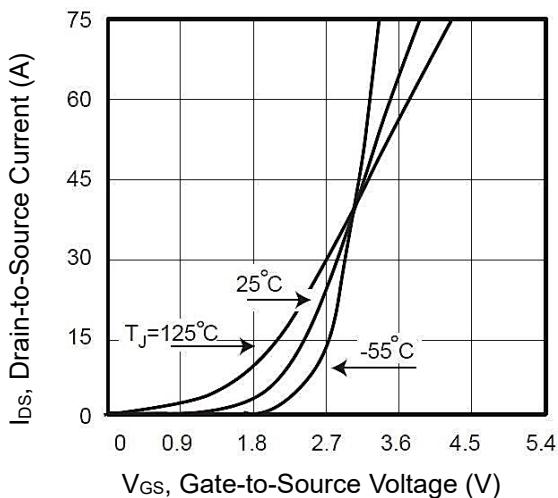
MERITEK

CHARACTERISTIC CURVES

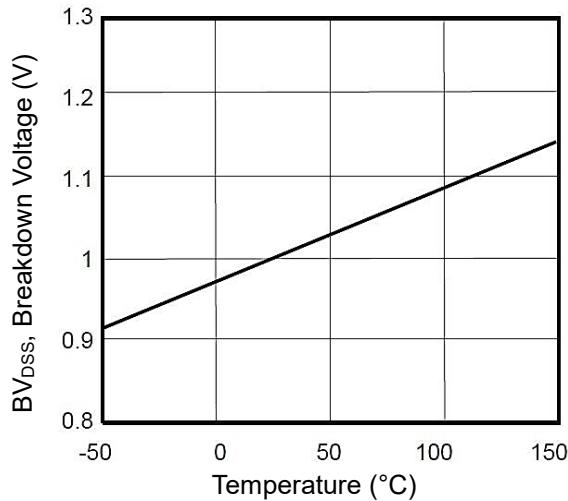
Output Characteristics



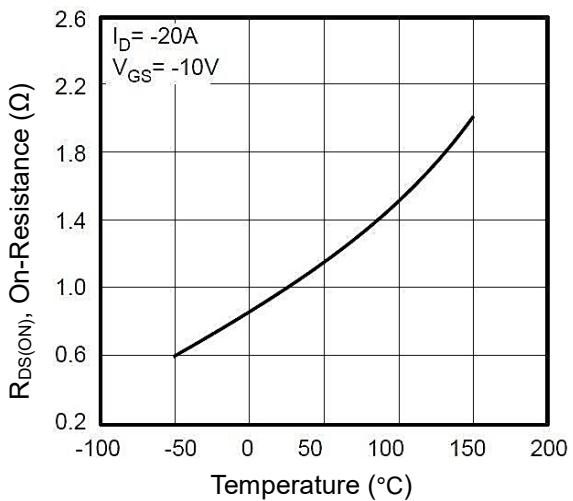
Transfer Characteristics



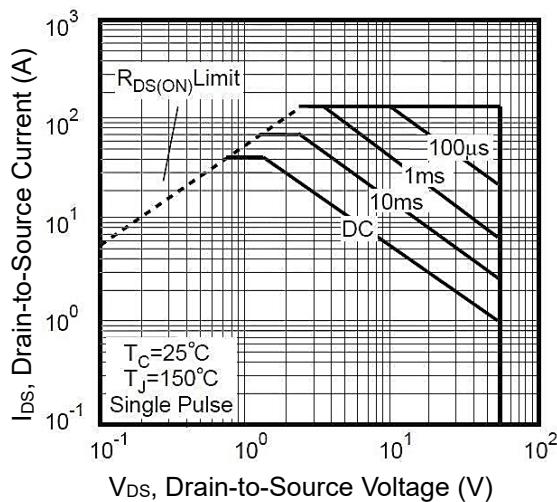
Threshold Voltage Variation with Temperature



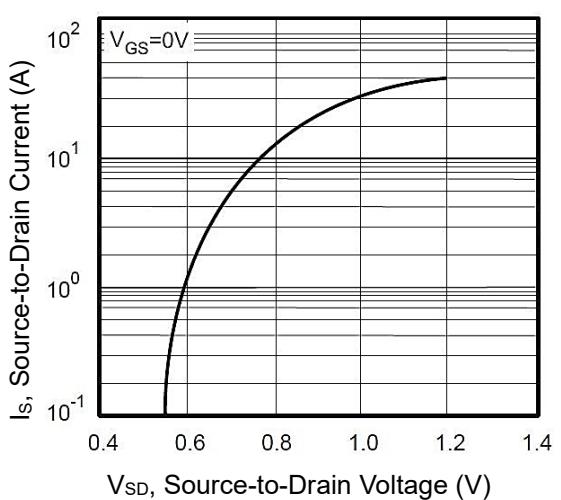
On-Resistance vs. Junction temperature



Maximum Safe Operating Area

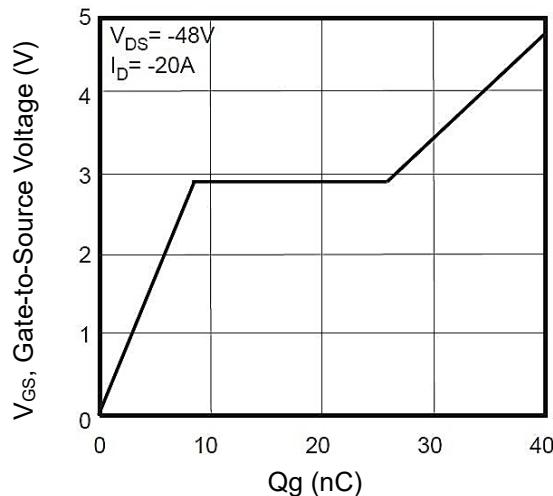


Body Diode Characteristics

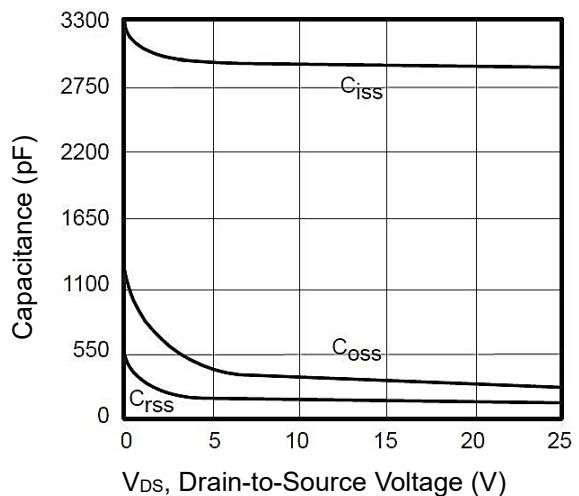


CHARACTERISTIC CURVES

Gate-Charge Characteristics



Capacitance vs. Drain-Source Voltage



Normalized Transient Thermal Impedance vs Pulse Width

